

500mA Power Distribution Switch

■ FEATURES

- 120mΩ (5V Input) High-Side MOSFET Switch.
- 500mA Continuous Load Current.
- 80µA Typical On-State Supply Current.
- 1µA Typical Off-State Supply Current.
- Current-Limit / Short Circuit Protection.
- Thermal Limiting Protection under Overcurrent Condition.
- Output can be Forced Higher than Input (Off-State).
- Active-High or Active-Low Enable.

■ APPLICATIONS

- Power Management.
- PCI Cards With Wake-On- LAN
- Hot Plug-In Power Supplies.
- Power Distribution Switch.

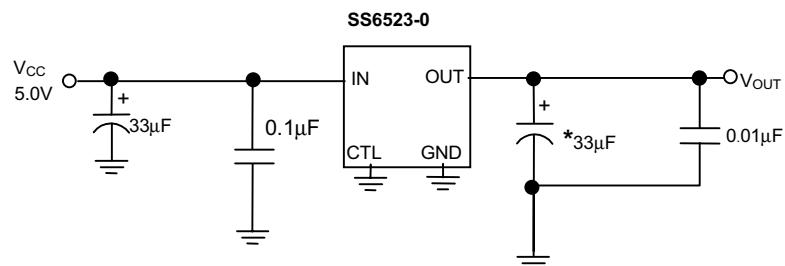
■ DESCRIPTION

The SS6523 is an integrated high-side power distribution switch for input power selection applications that using in portable products or PCI interface peripheral cards. The high-side switch is a MOSFET with 120mΩ R_{DS(ON)}, low voltage drop and low power consumption meet power saving requirements. The switch ON/OFF is controlled by CTL pin.

Output current is typically limited to 1.0A, well below the 5A safety requirement, and thermal shutdown function shuts the switch off to prevent damage under overcurrent conditions.

Design easily and layout flexibility for getting stable voltage in power transfer transition for power selection application. Guaranteed minimum output rise time limits inrush current during hot plug-in, minimizing EMI and preventing the voltage at upstream port from dropping excessively.

■ TYPICAL APPLICATION CIRCUIT



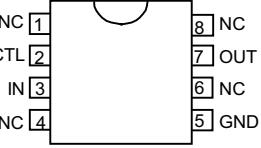
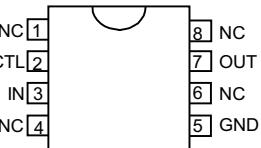
* 33µF, 16V Tantalum, or
 100µF, 10V Electrolytic
 Bold line indicate high-current traces

High-Side Power Distribution Switch

■ ORDERING INFORMATION

SS6523-XCXXX

- PACKING TYPE
TR: TAPE & REEL
TB: TUBE
- PACKAGING TYPE
O: MSOP
S: SO8
- CONTROL POLARITY
0: Active Low
1: Active High

PIN CONFIGURATION	
MSOP8 TOP VIEW	 NC [1] 8 NC CTL [2] 7 OUT IN [3] 6 NC NC [4] 5 GND
SO-8 TOP VIEW	 NC [1] 8 NC CTL [2] 7 OUT IN [3] 6 NC NC [4] 5 GND

 Example: **SS6523-0COTR**

→ Active Low Version in MSOP
 Package & Taping & Reel Packing

■ ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V_{IN}).....	7.0V
Operating Temperature Range	-40°C ~ 85°C
Storage Temperature Range	-65°C ~ 150°C

■ ELECTRICAL CHARACTERISTICS ($V_{IN} = 5V$, $T_A = 25^\circ C$, unless otherwise specified.)

PARAMETERS	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply Current	Switch Off, OUT=Open Switch On, OUT=Open		0.75 80	2 100	µA
Control Input Voltage	$V_{CTL} = \text{Logic "0"}$ $V_{CTL} = \text{Logic "1"}$			0.8	V
Control Input Current	$V_{CTL} = \text{Logic "0"}$ $V_{CTL} = \text{Logic "1"}$	2.4		0.01 0.01	µA
Output MOSFET Resistance	$I_{OUT} = 500\text{mA}$		120	180	mΩ
Output Turn-On Rise Delay	$R_L = 10\Omega$		30		µS
Output Turn-On Rise Time	$R_L = 10\Omega$		500		µS
Output Turn-Off Delay	$R_L = 10\Omega$		0.2	10	µS

■ ELECTRICAL CHARACTERISTICS (Continued)

PARAMETERS	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Output Turn-Off Fall Time	$R_L = 10\Omega$		0.2	10	μs
Output Leakage Current				2	μA
Current Limit Threshold	$V_{in} = 5.0\text{V}$	0.6	1.0	1.25	A
Current Limit Threshold	$V_{in} = 2.4\text{V}$	0.6			A
Thermal Limit			110		$^{\circ}\text{C}$

■ TYPICAL PERFORMANCE CHARACTERISTICS

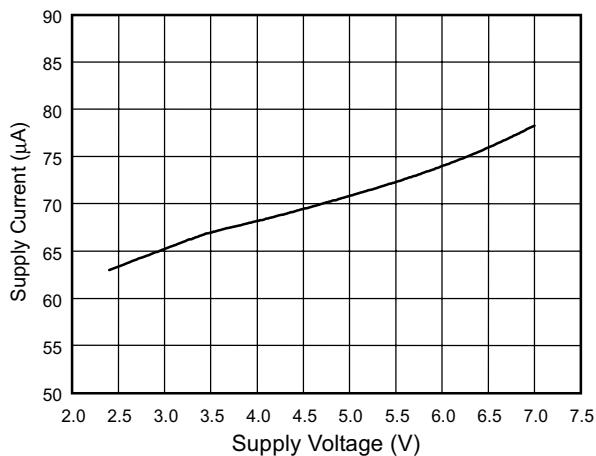


Fig. 1 On-State Supply Current vs. Supply Voltage

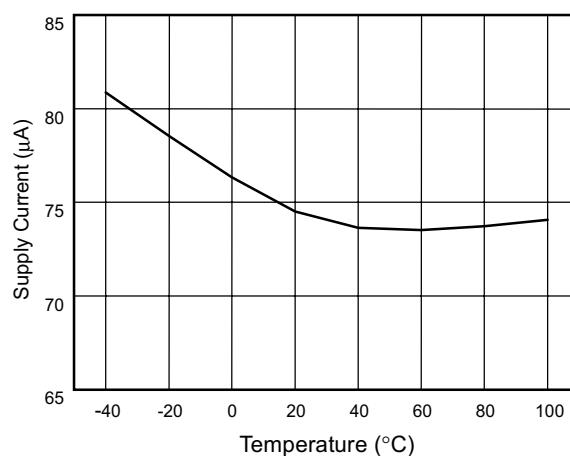


Fig. 2 On-State Supply Current vs. Temperature

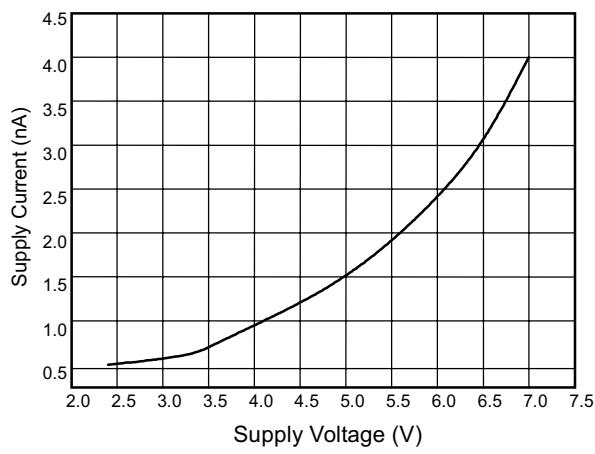


Fig. 3 Off-State Supply Current vs. Supply Voltage

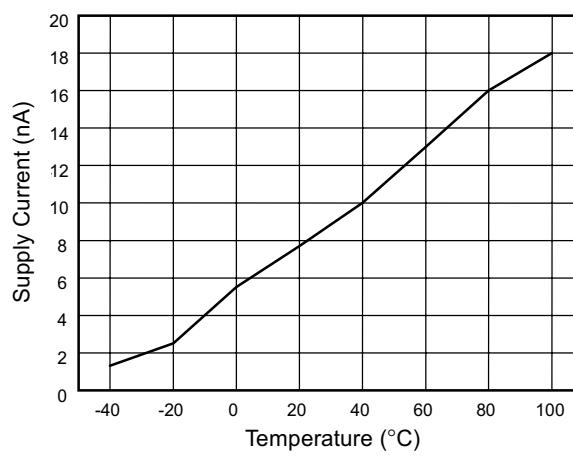


Fig. 4 Off-State Supply Current vs. Temperature

■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

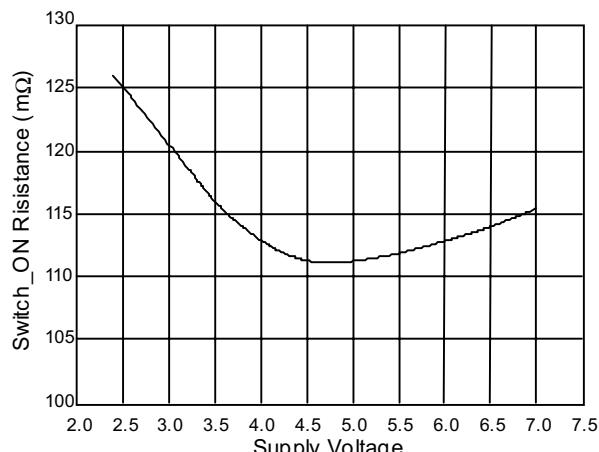


Fig. 5 Output On Resistance vs. Supply Voltage

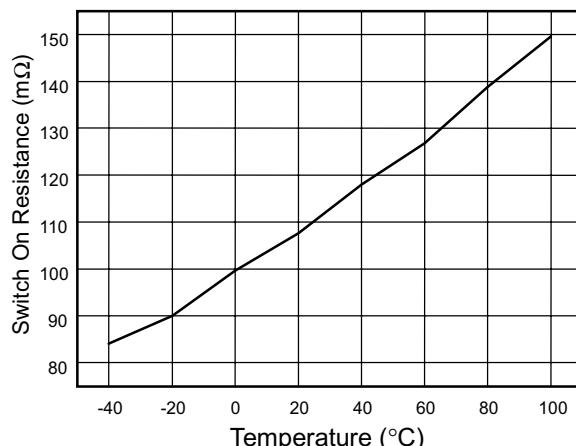


Fig. 6 Output On Resistance vs. Temperature

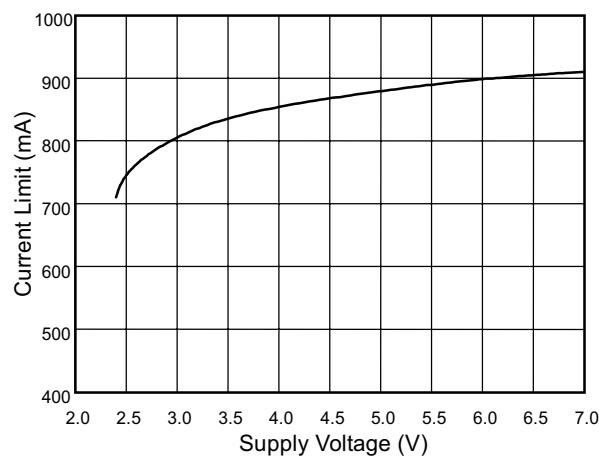


Fig. 7 Current Limit vs. Supply Voltage

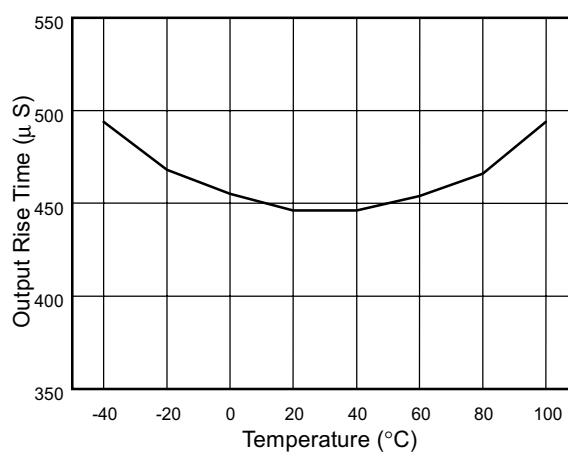


Fig. 8 Output Rise Time vs. temperature

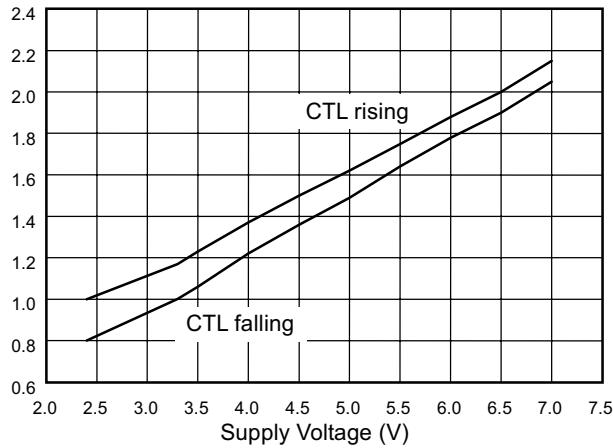


Fig. 9 CTL Threshold Voltage vs. Supply Voltage

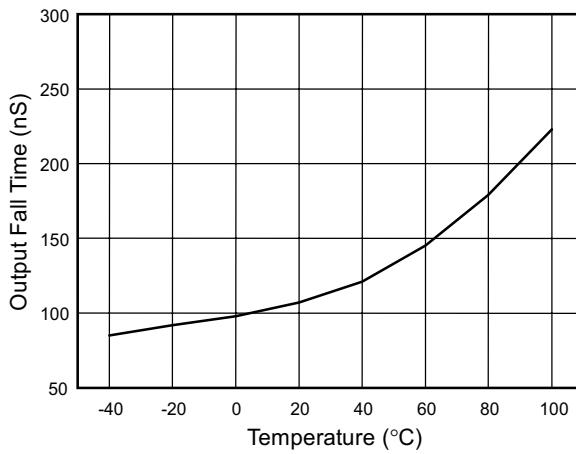


Fig. 10 Output Fall Time vs. Temperature

■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

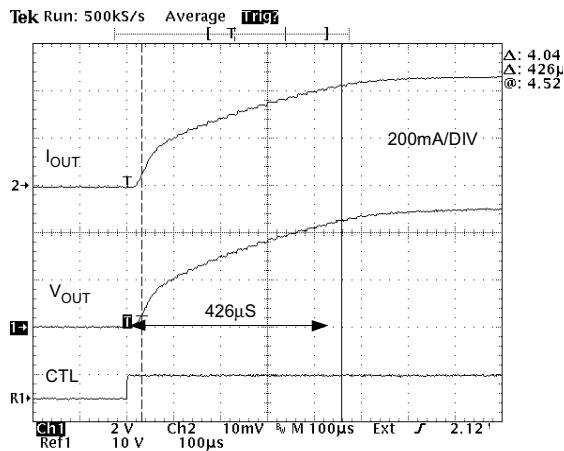


Fig. 11 Turn On Rising Time (10 Ω loading)

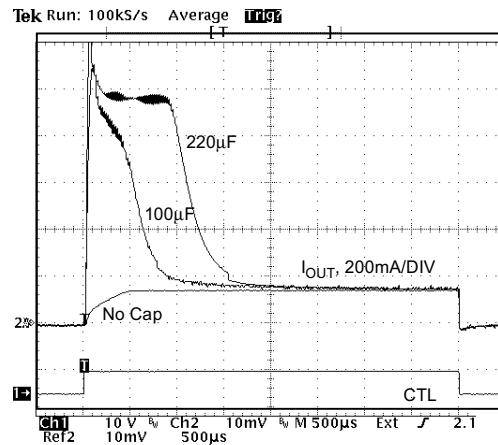


Fig. 12 Turn On Characteristic (35 Ω , Loading)

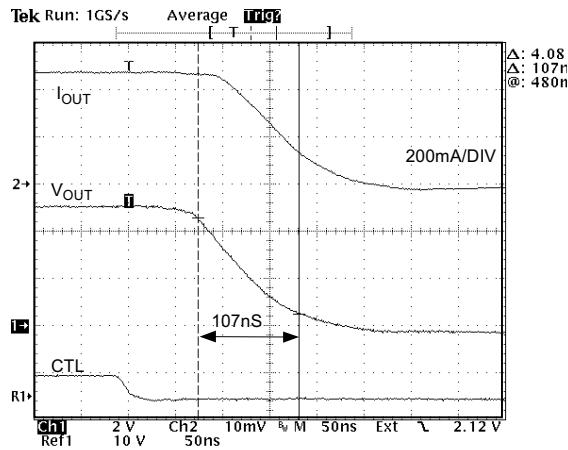


Fig. 13 Turn Off Falling Time (10 Ω Loading)

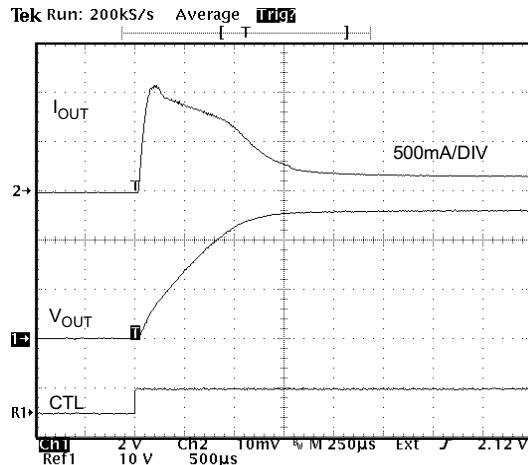


Fig. 14 Turn On Characteristic (35 Ω , 100 μ F Loading)

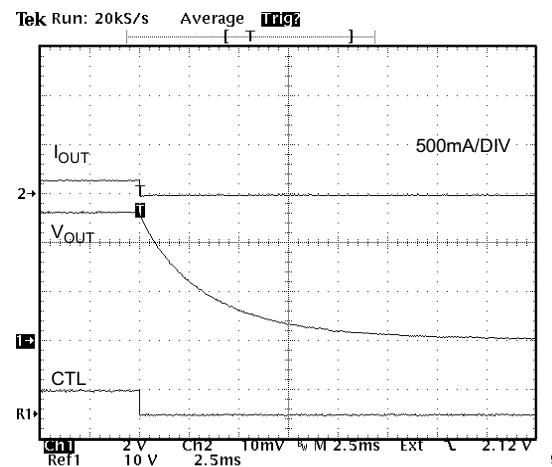


Fig. 15 Turn Off Falling Time (35 Ω , 100 μ F Loading)

■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

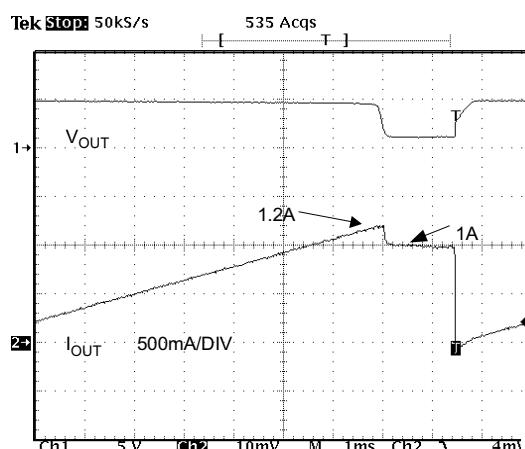


Fig. 16 Current Limit Threshold

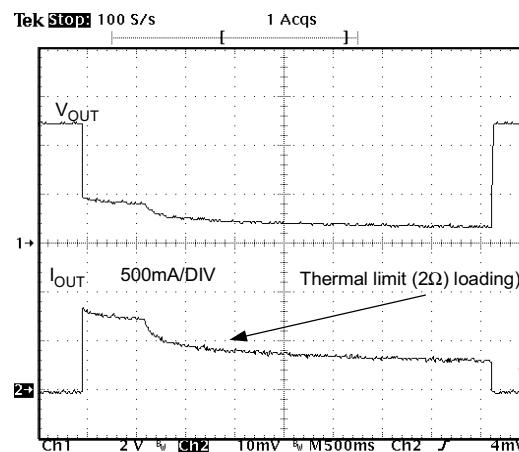


Fig. 17 Thermal Limiting Transient Response

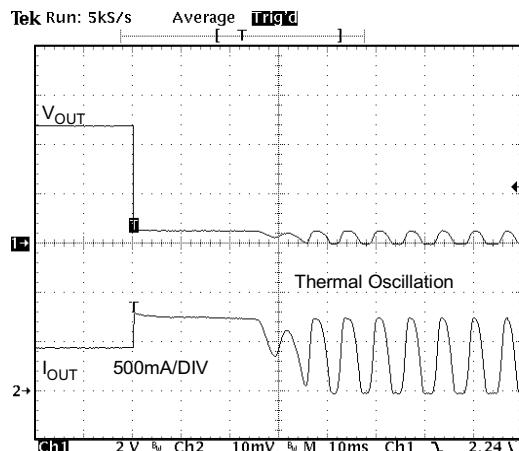


Fig. 18 Short Circuit Testing

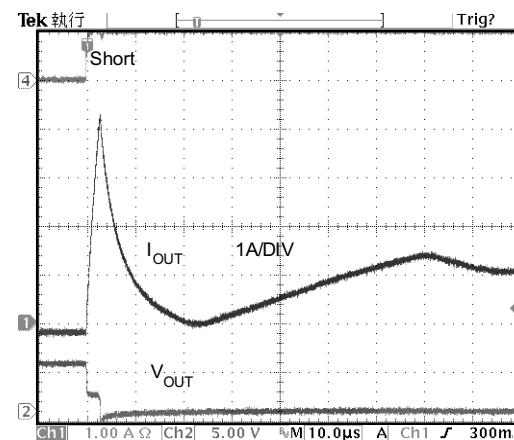
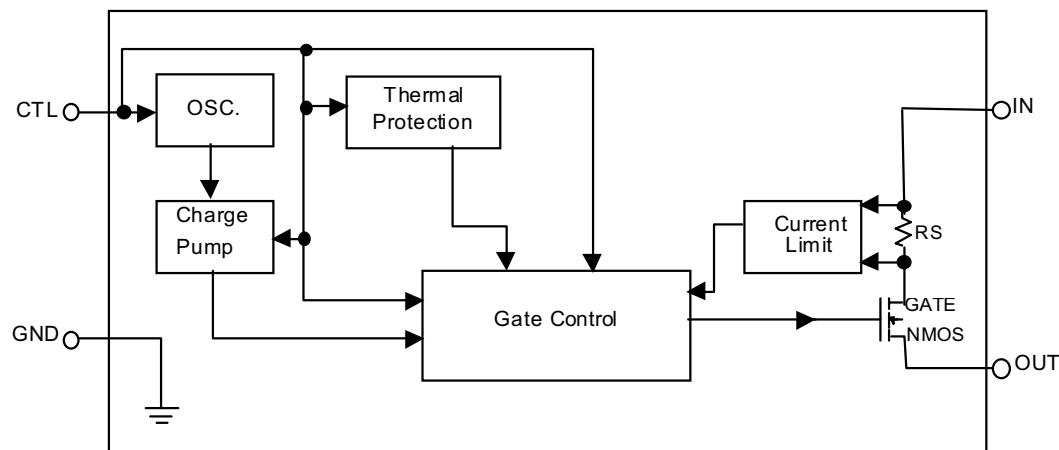


Fig. 19 Short Circuit Response Time

■ BLOCK DIAGRAM



■ PIN DESCRIPTION

PIN 1/4/6/8: NC:

PIN 2: CTL - TTL compatible control input. It controls the power switch turn-on/turn-off. Active High for SS6523-1 and active low for SS6523-0.

PIN 3: IN- Power supply input.

PIN 5: GND- Chip power ground.

PIN 7: OUT- MOSFET switch output.

■ APPLICATION INFORMATIONS

Current Limit

The current limit threshold is preset internally. It protects the output MOSFET switches from damage due to undesirable short circuit conditions or excess inrush current often encountered during hot plug-in. The SS6523 allows minimum 500mA continuous load current per Channel.

Thermal Protection

When the chip temperature exceeds 110°C, the thermal protection function works.

Supply Filtering

A 0.1uF to 1uF bypass capacitor from IN to GND, located near the device, is strongly recommended to control supply transients. Without a bypass capacitor, an output short may cause sufficient ringing on the input (from supply lead inductance) to damage internal control circuitry.

Transient Droop Requirements

A current surge is caused by the input capacitance of device. Ferrite beads are recommended in series with all power and ground connector pins. Ferrite beads reduce EMI and limit the inrush current during hot-attachment by filtering high-frequency signals.

Short Circuit Transient

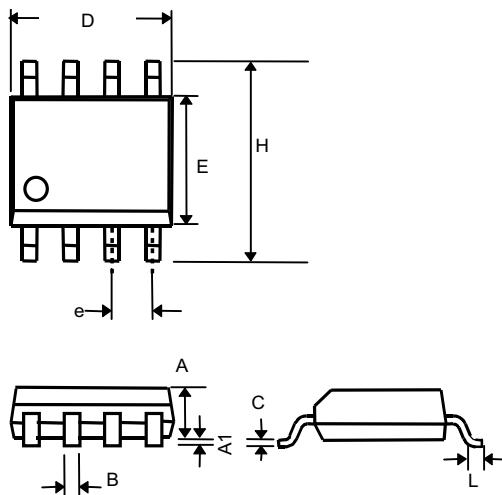
Bulk capacitance provides the short-term transient current needed during a hot-attachment event. With a 33uF, 16V tantalum or 100uF, 10V electrolytic capacitor mounted close to downstream connector should provide transient drop protection.

Printed Circuit Layout

The power circuitry of printed circuit boards requires a customized layout to maximize thermal dissipation and to minimize voltage drop and EMI.

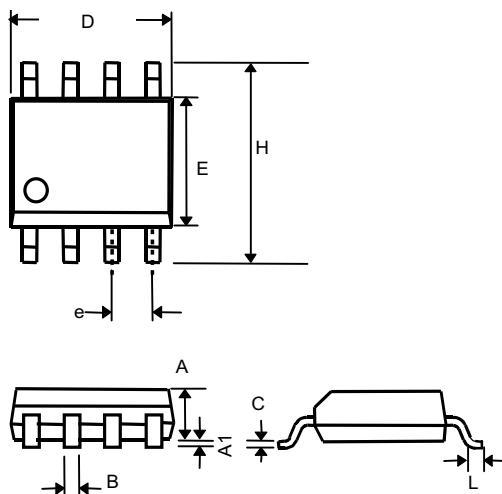
■ PHYSICAL DIMENSIONS

- **MSOP 8 (unit: mm)**



SYMBOL	MIN	MAX
A	0.76	0.97
A1	--	0.20
B	0.28	0.38
C	0.13	0.23
D	2.90	3.10
E	2.90	3.10
e	0.65	
H	4.80	5.00
L	0.40	0.66

- **8 LEAD PLASTIC SO (unit: mm)**



SYMBOL	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27(TYP)	
H	5.80	6.20
L	0.40	1.27

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